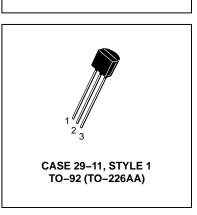
Switching Transistor NPN Silicon

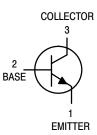
MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	15	Vdc
Collector-Emitter Voltage	V _{CES}	40	Vdc
Collector-Base Voltage	V _{CBO}	40	Vdc
Emitter-Base Voltage	V _{EBO}	5.0	Vdc
Collector Current — Continuous — 10 μs Pulse	Ι _C	300 500	mAdc
Total Device Dissipation @ T _A = 25°C Derate above 25°C	P _D	625 5.0	mW mW/°C
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	1.5 12	Watts mW/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to +150	°C



MPS3646

ON Semiconductor Preferred Device



THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Ambient	R_{\thetaJA}	200	°C/W
Thermal Resistance, Junction to Case	$R_{\theta JC}$	83.3	°C/W

ELECTRICAL CHARACTERISTICS (T_A = 25° C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage	$(I_{C} = 100 \ \mu Adc, \ V_{BE} = 0)$	V _{(BR)CES}	40	-	Vdc
Collector – Emitter Sustaining Voltage ⁽¹⁾	$(I_{\rm C} = 10 \text{ mAdc}, I_{\rm B} = 0)$	V _{CEO(sus)}	15	-	Vdc
Collector-Base Breakdown Voltage	$(I_{C} = 100 \ \mu Adc, I_{E} = 0)$	V _{(BR)CBO}	40	—	Vdc
Emitter-Base Breakdown Voltage	$(I_E = 100 \ \mu Adc, I_C = 0)$	V _{(BR)EBO}	5.0	—	Vdc
Collector Cutoff Current $(V_{CE} = 20 \text{ Vdc}, V_{BE} = 0)$ $(V_{CE} = 20 \text{ Vdc}, V_{BE} = 0, T_A = 65^{\circ}\text{C})$ ON CHARACTERISTICS ⁽¹⁾		I _{CES}	_	0.5 3.0	μAdc
DC Current Gain	$(I_{C} = 30 \text{ mAdc}, V_{CE} = 0.4 \text{ Vdc})$ $(I_{C} = 100 \text{ mAdc}, V_{CE} = 0.5 \text{ Vdc})$ $(I_{C} = 300 \text{ mA}, V_{CE} = 1.0 \text{ Vdc})$	h _{FE}	30 25 15	120 — —	-
Collector – Emitter Saturation Voltage		V _{CE(sat)}		0.2 0.28 0.5 0.3	Vdc
Base – Emitter Saturation Voltage	$(I_{C} = 30 \text{ mAdc}, I_{B} = 3.0 \text{ mAdc})$ $(I_{C} = 100 \text{ mAdc}, I_{B} = 10 \text{ mAdc})$ $(I_{C} = 300 \text{ mAdc}, I_{B} = 30 \text{ mA})$	V _{BE(sat)}	0.73 	0.95 1.2 1.7	Vdc

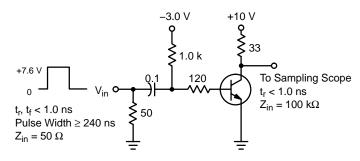
1. Pulse Test: Pulse Width \leq 300 µs; Duty Cycle \leq 2.0%.

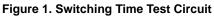
Preferred devices are ON Semiconductor recommended choices for future use and best overall value.



	Symbol	Min	Max	Unit	
SMALL-SIGNA	L CHARACTERISTICS				
Current-Gain — Bandwidth Product (I _C = 30 mAdc, V _{CE} = 10 Vdc, f = 100 MHz)		f _T	350	_	MHz
Output Capacitance ($V_{CB} = 5.0 \text{ Vdc}$, $I_E = 0$, f = 1.0 MHz)		C _{obo}	—	5.0	pF
Input Capacitance ($V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz}$)		C _{ibo}	—	9.0	pF
SWITCHING CH	IARACTERISTICS				
Turn–On Time		t _{on}	—	18	ns
Delay Time	(V _{CC} = 10 Vdc, I _C = 300 mAdc, I _{B1} = 30 mAdc) (Figure 1)	t _d	—	10	ns
Rise Time		tr	—	15	ns
Turn–Off Time	(V _{CC} = 10 Vdc, I _C = 300 mAdc, I _{B1} = I _{B2} = 30 mAdc)	t _{off}	—	28	ns
Fall Time	(Figure 1)	t _f	—	15	ns
Storage Time		t _s	_	18	ns

Storage Time $(V_{CC} = 10 \text{ Vdc}, I_C = 10 \text{ mAdc}, I_{B1} = I_{B2} = 10 \text{ mAdc}) \quad (Figure 2)$





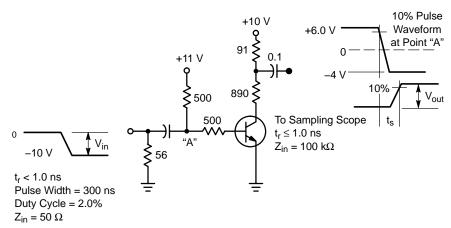
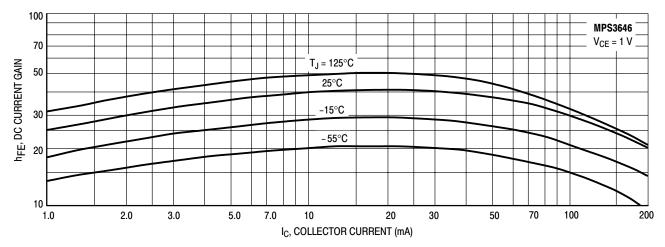


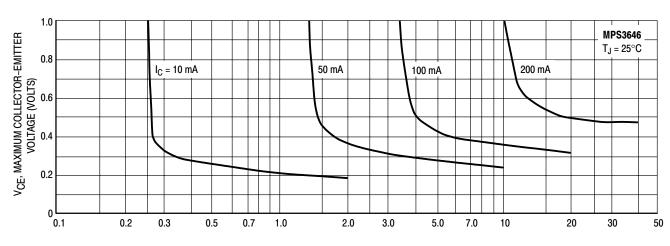
Figure 2. Charge Storage Time Test Circuit

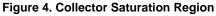
CURRENT GAIN CHARACTERISTICS

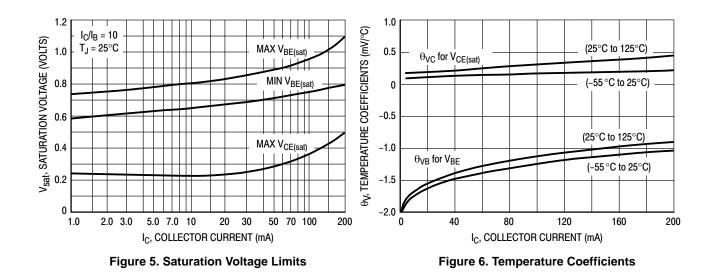




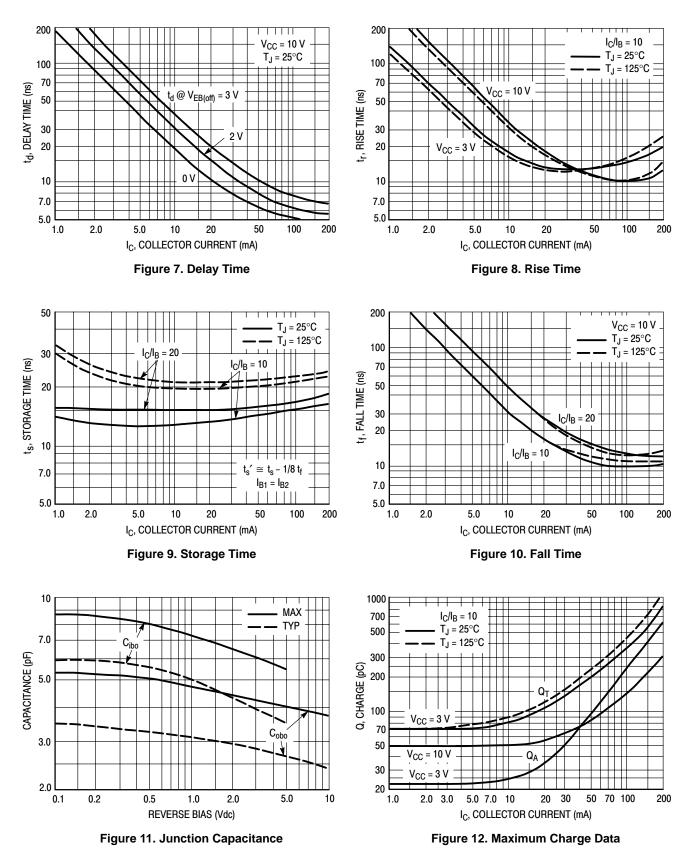
"ON" CONDITION CHARACTERISTICS





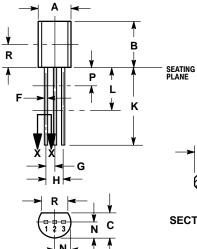


DYNAMIC CHARACTERISTICS



PACKAGE DIMENSIONS

CASE 029-11 (TO-226AA) ISSUE AD









- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. CONTROUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED. 4. DIMENSION F APPLIES BETWEEN P AND L. DIMENSIONS D AND J APPLY BETWEEN L AND K MIMIMUM. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.44	5.21
В	0.290	0.310	7.37	7.87
C	0.125	0.165	3.18	4.19
D	0.018	0.021	0.457	0.533
F	0.016	0.019	0.407	0.482
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.018	0.024	0.46	0.61
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
Ρ		0.100		2.54
R	0.135		3.43	

<u>Notes</u>

<u>Notes</u>

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